



Product Change Notification / RMES-15KLMX168

Date:

21-Jan-2021

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4502 Initial Notice: Qualification of NSEB as a new assembly site for ATTINY43x, ATTINYx4x, ATTINYx313x, ATTINY84x, ATTINY1634x, ATTINY44x, ATTINY13x, ATTINY85x, AT73C508, ATTINY45x, ATTINY25x and QT14C10 device families available in 20L WQFN (4X4X0.8mm) package.

Affected CPNs:

[RMES-15KLMX168_Affected_CPN_01212021.pdf](#)

[RMES-15KLMX168_Affected_CPN_01212021.csv](#)

Notification Text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as a new assembly site for ATTINY43x, ATTINYx4x, ATTINYx313x, ATTINY84x, ATTINY1634x, ATTINY44x, ATTINY13x, ATTINY85x, AT73C508, ATTINY45x, ATTINY25x and QT14C10

device families available in 20L WQFN (4X4X0.8mm) package.

Pre Change:

Assembled at ASKR site using palladium coated copper (PdCu) bond wire, EN-4900GC die attach material, lead frame without lead lock and ring plating DAP Surface Prep.

Post Change:

Assembled at NSEB site using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, lead frame with lead lock and Ag on lead only DAP Surface Prep.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Korea Inc. (ASKR)	UTAC Thai Limited (NSEB)
Wire material	PdCu	CuPdAu
Die attach material	EN-4900GC	8600
Molding compound material	G700	G700
Lead frame material	C194	C194
Lead Lock	No	Yes
DAP Surface Prep	Ring plating	Ag on lead only

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying NSEB as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

July 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen

business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2021					>	July 2021				
Workweek	01	02	03	04	05		27	28	29	30	31
Initial PCN Issue Date				X							
Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change:

Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

January 21, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-15KLMX168_Qual_Plan.pdf](#)

[PCN_RMES-15KLMX168_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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